

Material Content Data Sheet Collection

Sales Product Name	IGB03N120S7
MA#	SP005753189
Package	PG-TO263-3-2
Versions	123158,123159
Issued	26. August 2024



Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IGB03N120S7	**Issued**	26. August 2024
MA#	MA005876349		
Package	PG-TO263-3-2	**Weight***	1460.78 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.393	0.095	0.095	954	954
leadframe	inorganic material	phosphorus	7723-14-0	0.256	0.018	58.380	175	583799
	non noble metal	iron	7439-89-6	0.853	0.058		584	
	non noble metal	copper	7440-50-8	851.691	58.304		583040	
wire	non noble metal	aluminium	7429-90-5	0.977	0.067	0.067	669	669
encapsulation	inorganic material	zincoxide	1314-13-2	5.943	0.407	40.685	4069	406854
	miscellaneous	miscellaneous	-	23.773	1.627		16274	
	plastics	epoxy resin	-	89.148	6.103		61028	
	inorganic material	silicondioxide	60676-86-0	475.458	32.548		325483	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.661	0.661	6611	6611
plating	inorganic material	phosphorus	7723-14-0	0.001	0.000	0.016	0	157
	non noble metal	nickel	7440-02-0	0.228	0.016		156	
solder	non noble metal	tin	7440-31-5	0.028	0.002	0.096	19	957
	noble metal	silver	7440-22-4	0.035	0.002		24	
	non noble metal	lead	7439-92-1	1.335	0.091		914	
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com



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MA#	MA005876349		
Package	PG-TO263-3-2	**Weight***	1460.77 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.393	0.095	0.095	954	954
leadframe	inorganic material	phosphorus	7723-14-0	0.256	0.018	58.380	175	583803
	non noble metal	iron	7439-89-6	0.853	0.058		584	
	non noble metal	copper	7440-50-8	851.691	58.304		583044	
wire	non noble metal	aluminium	7429-90-5	0.943	0.065	0.065	645	645
encapsulation	inorganic material	zincoxide	1314-13-2	5.943	0.407	40.687	4069	406873
	miscellaneous	miscellaneous	-	23.774	1.627		16275	
	plastics	epoxy resin	-	89.152	6.103		61031	
	inorganic material	silicondioxide	60676-86-0	475.478	32.550		325499	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.661	0.661	6611	6611
plating	inorganic material	phosphorus	7723-14-0	0.001	0.000	0.016	0	157
	non noble metal	nickel	7440-02-0	0.228	0.016		156	
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